



ZILIAN
子聯有限公司

SINGAPORE

• 新加坡

MALAYSIA

• 馬來西亞

TAIWAN

• 台灣

Semiconductor Equipment & Solution Provider

Technology Transfer and Resource Integration in collaboration with worldwide partners.

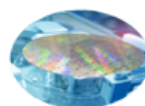
EXCELLENT



- ✓ Meet customer needs
- ✓ Reliable partner
- ✓ Trustworthy



Wet Process, Etching,
Stripper, Scrubber



Chemical - Etching,
Stripper, Plating



Photolithography
Track



Direct Write
Lithography



Furnace &
Auto Oven



Microscope &
Metrology



Advance Packaging
Wafer Probe



Wafer Bonder &
Debonder



Particle Counter



Purifying Filter
System



Metal Carrier



Smart Zi Lian -
Intelligent Cabinet



Spin Rinse Dryer
SV SH SRD



TC Wafer:
Thermocouple Wafer

Lamination Film

FOUP / Cassette
/ Magazine

PCB Board

Mechanical

Pack Unpack
Line

Greene Tweed
O-Ring

Facility

AE
Power Supply

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Panel Level Processor

Oxidation Wet Etching Stripper



UFO Series

Application:

- UBM Etch
- PR Strip
- PR Developer
- PI Developer
- Scrubber

Features:

- Soft Spray Pressure Clean
- Chemical Reclaim Function
- High Warpage Handling
- Backside Protection
- Continuous Process

Single Wafer Processor

Excellent for Advanced Process



Features:

- End Point Detector
- Soft Spray Pressure Clean
- Multi-Chemical Reclaim Function
- High Warpage Handling
- De-bubble Module
- Continuous Process

UFO Series

Applications:

- Scrubber
- Flux Clean
- Mask Clean

Features:

- High Productivity
- Hot DIW System
- High Pressure Clean

Wet Bench

Fully Customize



VAN Series

Applications:

- Metal/Si/Oxide/Nitride Etch
- PR Strip
- RCA Clean
- Cu Electroplating
- Electroless Plating
- Glass Clean

Features:

- Chemical Mixing and Spiking
- High Temperature Control
- High Warpage Handling
- Agitation
- Megasonic System
- Dry In Dry Out
- Auto PM
- High Throughput
- Special Cassette Design

No. 1 UBM Etchant Supplier

Etchant

IC Package

- Cu, Ti, TiW, Au, Ag, NiV, Cr, Au, Bump Rework

Si

- BGBM/ TSV/ MEMS

Antiglare Glass

No. 1 Non-DMSO, Non-NMP Stripper Supplier

Stripper

IC Package

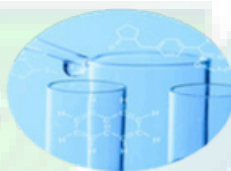
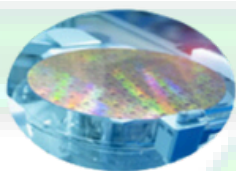
- Dry Film
- Spin on resist (pos./neg.)
- Adhesive

World 1st nt-Cu Additive Supplier

ECD Chemicals

nt-Cu Additive

- RDL
- Cu-Cu Direct Bond
- Cu Foil for Li-Battery



Cu Etchant

Application

- Fine line RDL
- Copper pillar bump & C4 bump
- Cu/Ni/Au RDL and Ni/Au pad

Features

- Low Cost of Ownership (CoO)
- High etching rate, up to 250 Å/sec
- Long bath life, up to 120 hrs
- High wafer loading, up to 20 wafers/L
- Profile integrity
- Fine pitch bump enabling technology:
- -High aspect ratio, up to 1:6
- -Small bump space, down to 4 μm
- -Small undercut & CD loss

Cu-125

RDL, CPB, LF Bump

Cu-128

RDL, CPB, LF Bump

Cu-6047

Fine Line RDL, CPB, LF Bump

Cu-6039

HBM (Ni/Au Device)

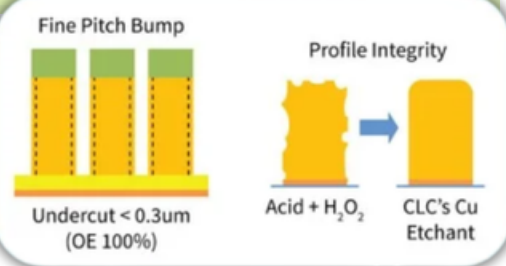
Ti Etchant

Application

- Fine line RDL
- Copper pillar bump (CPB)
- LF Bump

Features

- Process Compatibility – minimal Al, Cu, SnAg attack
- Free of Na, K, F
- Stable bath temperature
- Wide selection – acid/base ready-to-use system
- Alkaline base additive available



Ti-8020-S

RDL, CPB, LF Bump

Ti-899M

RDL, CPB, LF Bump

Ti-890

RDL, CPB, LF Bump

Ti-9027-B

RDL, CPB, LF Bump

CST-1725

RDL, CPB, LF Bump

Application:

- Positive PR stripping
- Multi-layer PI / PBO passivation

Features:

- Eco-Friendly series (non-NMP, non-DMSO, non-TMAH)
- No cracks with multi-layer PI
- Workable with positive PR (~60 μm)
- Inherits all general PR Stripper capabilities

CST-161

Fine Line RDL, CPB, LF Bump

Application:

- Negative PR stripping
- Dry Film PR stripping
- Multi-layer PI / PBO passivation

Features:

- DMSO series
- Workable with negative PR
- Workable with dry film PR (thickness up to 120 μm)
- Inherits all general PR Stripper capabilities

Au-800A

Gold Bump

Application:

- UBM etch
- Gold bump rework

Features:

- KI / I₂ series chemistry
- Al protection
- Au Etching Rate: 160 Å/sec (32°C)
- Inherits all general Au Etchant capabilities

Ni-636E

RDL, CPB, LF Bump

Application:

- Nickel bump rework
- Redistribution layer (RDL) etching
- Copper pillar bump (CPB)
- LF Bump

Features:

- Nitric acid series
- Cu Etching Rate: 1,000 Å/sec (28°C)
- Ni Etching Rate: 100 Å/sec (28°C)
- Inherits all general Bump Rework capabilities

Water-cooled Oxygen-free oven / Water-cooled Precision Oven

Precision Forced-air Oven / Precision Forced-air Drying Oven / Nitrogen-filled Forced-air Oven



Wafer Size:

- Supports semiconductor wafers
- Chamber size customizable
- Suitable for IC, CMOS, TSV, MEMS, DB/WB, FPD processes

Applications:

- Wafer baking and drying
- IC curing (DB/WB)
- Semiconductor back-end process
- FPD and precision electronic components
- Electronic ceramics and materials

Features:

- Precision forced-convection heating
- Optional nitrogen (oxygen-free) or water-cooled design
- Temperature range: RT ~ 300°C
- Stability: $\pm 1^\circ\text{C}$
- Uniformity: $\pm 2\%$ @260°C
- SUS304 stainless steel chamber
- Single or dual chamber available

Dust-free Ovens, Clean Drying Ovens

High-temperature Oxygen-free Oven / Anti-oxidation Curing Oven / High-temperature Oxygen-free Curing Oven / High-temperature Anaerobic Curing Oven



Wafer Size:

- Semiconductor wafers (customizable)
- Supports wafer-level processes (CMOS, TSV, MEMS, Bumping)

Applications:

- Wafer baking & drying
- Photoresist / PI / BCB curing
- Wafer-level thermal process
- Oxygen-free high-temperature curing
- Semiconductor front-end clean processing

Features:

- Class 100 clean environment (HEPA)
- Nitrogen / oxygen-free atmosphere
- Max temperature up to 450°C
- Stability $\pm 1^\circ\text{C}$, uniformity $\pm 2\%$
- SUS304 / SUS316 stainless chamber
- Fast heating, high-efficiency insulation
- PLC control, multi-alarm protection

Fully Automatic Oven



Wafer Size:

- Semiconductor wafers (customizable)
- Compatible with wafer-level and packaging processes
- Supports DB / WB / FPD applications

Applications:

- Wafer baking and drying
- IC curing (DB/WB)
- Precision thermal processing
- High-precision electronic components
- Semiconductor and display manufacturing

Features:

- Fully automatic multi-chamber design
- High temperature, high cleanliness
- Automatic door system
- AGV-compatible automatic loading/unloading
- Compact multi-layer structure
- Uniform heating and cooling
- Process temperature: RT +30°C ~ 300°C

Ultra-high Vacuum Oven / High Vacuum Oven

Fully Automatic Vacuum Degassing Furnace



Wafer Size:

- Semiconductor wafers (customizable)
- Suitable for wafer vacuum bake and HMDS processes

Applications:

- Wafer vacuum baking
- High-temperature HMDS processing
- Vacuum degassing and drying
- Semiconductor back-end thermal process
- Electronic components and materials treatment

Features:

- Ultra-high vacuum, high-temperature operation
- Fully automatic continuous system
- Integrated HMI control
- Fast, uniform plate heating
- Magnetic-fluid seal, no vacuum leakage
- High-cleanliness stainless steel chamber

HMDS Pretreatment System / HMDS Coating Machine

Vacuum High-Temperature Oxygen-Free Oven / Vacuum Anti-Oxidation Curing Oven / Vacuum High-Temperature Anaerobic Curing Oven



Wafer Size:

- Semiconductor wafers (customizable)
- Batch processing (multi-cassette support)

Applications:

- HMDS vapor priming / dehydration bake
- Photoresist adhesion enhancement
- Wafer vacuum bake
- High-temperature oxygen-free curing
- Front-end semiconductor thermal processes

Features:

- Integrated dehydration bake + HMDS vapor process
- Closed vacuum system, clean and safe
- Ultra-high vacuum $\leq 10\text{ Pa}$
- Oxygen content: $\leq 30\text{ ppm}$ (high temp)
- Max temperature up to 450°C
- Stability $\pm 1^\circ\text{C}$, uniformity $\leq 2\%$
- Fast heating and cooling
- Ceramic heaters, ceramic fiber insulation
- Class 100 clean level

Fully Automatic Vertical Tube Furnace (PIQ, Annealing, Alloy)

Fully Automatic Vacuum Vertical Oven



Wafer Size:

- Semiconductor wafers (customizable)
- Batch processing supported

Applications:

- Vertical Tube Furnace:**
- BPO / PI / BCB curing
 - Wafer annealing & alloying
 - IC processes (CMOS, TSV, MEMS, Bumping, fingerprint sensors)

Vacuum Vertical Oven:

- Vacuum baking & drying
- Dehydration, degassing, curing
- Semiconductor and compound semiconductor processes

Features:

- Fully automatic continuous operation
- Integrated HMI control system
- Fast, uniform heating (FEC / ceramic fin heaters)
- High-cleanliness stainless steel chamber
- Physical & chemical polished surfaces
- High-temperature self-cleaning function (tube furnace)
- Ultra-high vacuum $\leq 10\text{ Pa}$ (vacuum oven)
- Optional low oxygen control ($\leq 30\text{ ppm}$ at high temp)

WLP 2000

Wafer Level Package Direct Writing Lithography System



Application & Features:

- Wafer-level packaging
- Supports multi-die and full-surface die applications
- Maskless direct writing exposure
- DMD scanning lithography
- High-performance data processing
- CFMEE optical lenses
- High imaging quality and accuracy
- Flexible operation and functions
- Lower cost
- Faster cycle time
- Higher yield

PLP 3000

Panel Level Package Direct Writing Lithography System



Application & Features:

- Industry-leading digital lithography for panel-level packaging
- High resolution, 3 μ m lines and spaces
- High overlay accuracy, $\pm 2 \mu$ m
- Intelligent zone compensation exposure for optimal patterning
- Smart RDL rerouting for flexible design
- Nano-level real-time auto focusing for precision
- Automatic edge detection support
- Handles high substrate warpage
- Compatible with CFMEE integrated measurement, exposure, and inspection solutions

MLF

Direct Writing Lithography System Series

Application & Features:

- Industry-leading digital lithography for high-precision applications
- High throughput for efficient processing
- High aspect ratio for fine features
- High overlay accuracy for precise alignment
- High precision platform for stable and accurate exposure
- Edge alignment and centered exposure
- User-defined marking for customization
- Various magnification objectives for flexibility
- Optional backside alignment for advanced processing
- Optional auto load and unload system for higher efficiency

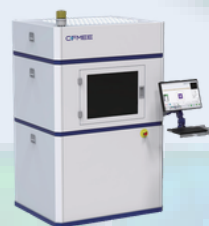


MLC

Direct Writing Lithography System Series

Application & Features:

- Micro and nano device fabrication, photomask writing, and 3D structure lithography
- Automatic alignment with user-defined alignment marks
- Visual exposure function
- Fast and fine exposure modes
- Auto focusing for high precision
- Supports irregular sample exposure
- Compatible with GDSII, Gerber, and ODB++ data formats
- Optional backside alignment
- 405 nm LD light source, 375 nm optional

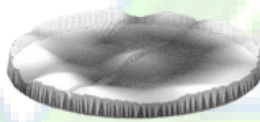
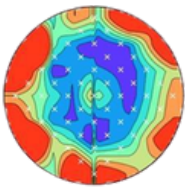


達裕科技
I-BOT TECHNOLOGY

Wafer Bumping 4PP, Probe System & XRF

WRM320

4PP Thickness Measurement



Application & Features:

- Bumping FAB for HBM
- Cu pillar
- Fan-out
- 2.5D and 4D packaging
- CoWoS
- Wafer metal film thickness measurement for precise evaluation

WPM320

Auto RS_ Leakage Measurement



Application & Features:

- Bumping FAB for HBM
- Cu pillar
- Fan-out
- 2.5D and 3D packaging
- CoWoS
- Wafer auto RS leakage measurement for precise evaluation

WXR320

Fully Auto XRF Measurement



Application & Features:

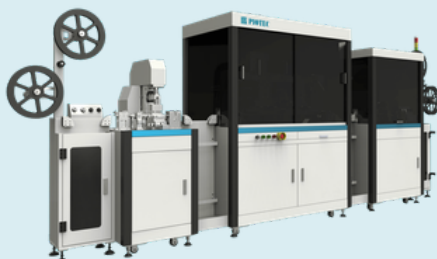
- Bumping FAB for HBM
- Cu pillar
- Fan-out
- 2.5D and 5D packaging
- CoWoS
- Quantitative analysis of Sn-Ag, Sn, Ag, Cu, and Ni



Smart Card & Sim Card Assembly System

PTM-120T

Chip Module Initialization and Testing Machine



Applications:

- Unwinding, testing, re-testing, rejection, and rewinding of chips and tapes.

Features:

- Unwinding Module
- Initialization/Testing Module
- Re-Initialization/Re-testing Module
- Reject Chip Punching Module
- Rewinding Module
- Short-circuit Punching Module (Optional)



All type Auto 2D/ 3D Microscope & Macro with AI Equipment, Desk Type Wafer Transfer System

KINO-3200

Metrology



Applications:

- Connects to various front-end EFEM systems, including Wafer robot, Table loader, and Frame wafer loader.
- Paired with AOI+AI image detection module for online detection and classification.

Features:

- Equipped with active laser automatic real-time focus for precise alignment.
- Supports flying shooting mode.
- Offers customized functional combinations such as dual optical simultaneous detection, infrared optical detection, 3D interference/confocal optical measurement, and high-magnification re-inspection system.

Kino Wafer Loader & INT 3000

Wafer Sorter/Loader & Automated Inspection System



Wafer Size:

- Supports ultra-thin wafers down to 150 μm
- Designed for third-generation semiconductor materials

Applications:

- Wafer loading, sorting, and transfer
- AI sampling and re-inspection
- Defect review and automatic measurement
- Compatible with microscopes and white-light interferometry (confocal) systems
- Automated inspection for semiconductor production lines

Features:

- Fully automated loading, positioning, imaging, and data storage
- **SEMI S2 & S8** certified, patented design
- Solves edge alignment issues of transparent/translucent wafers
- Automatic defect map conversion and import
- CD / Overlay automatic measurement
- AI-based auto re-judgment to improve accuracy
- MES connectivity with automatic data upload
- Built-in offline image analysis database



High Vacuum Plasma & Wafer Thinning Solution

Lift-Off
PVD

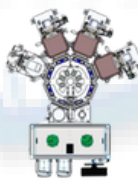
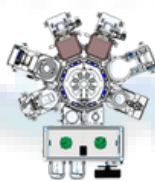
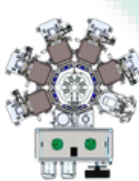
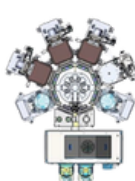
LED AlN
Buffer
Layer

IGBT &
MOSFET

FEOL
(AlCu + TTN)

Advanced
Package

Gold Bump
/ Bumping



Silicon Semiconductor Frontend/Adv.
Package/IGBT BM (PVD, ALD, Bonder,
Descum, PECVD)

Compound Semiconductor
GaAs/InP/SiC/GaN
(PVD, ALD, Bonder, De-Bonder)

LED/Mini LED/ Micro LED (PVD, ALD)
& (QD Solution)

CPO (Co-Package Optics)
(Bonder, De-Bonder, PVD)

PLP (Panel Level Package)
(PVD, Descum, Etching)

t-ALD +
Pre-treatment

PEALD NBT
/ C2PT

Powder t-
ALD Al_2O_3

Descum /
Plasma Polish

PECVD



High Vacuum & Plasma

PVD

ALD

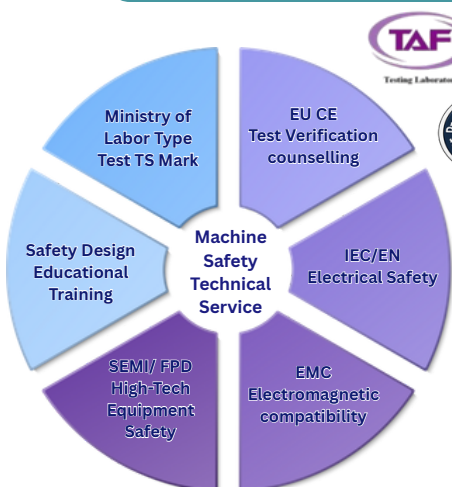
PECVD

Descum & Plasma Polish

Assisting domestic companies to meet international safety verification requirements in order to reduce the safety design and verification costs of domestic companies.

Qualified as International ISO 17065 Certification Institution

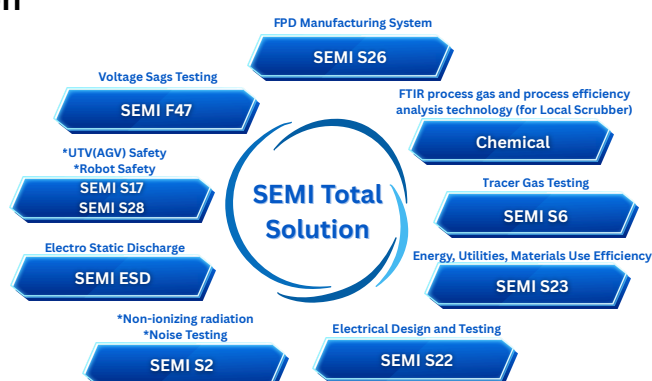
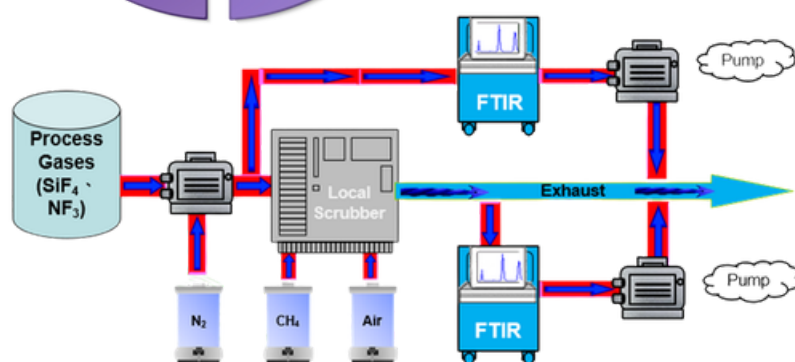
Qualified as International ISO 17025 Test Laboratory



PMC is one of the third-parties designated by tsmc and also a SEMI S2 testing and verification unit recognized by semiconductor factories such as UMC, Intel, Micron, and Global Foundries etc.



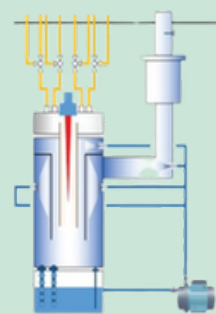
Real-time Monitoring
On site Inspection/Check
ISO Certification



苏州新耀环保科技有限公司

Local Scrubber : Exhaust Gas Heater Plasma / Absorber / Catalyst Scrubber

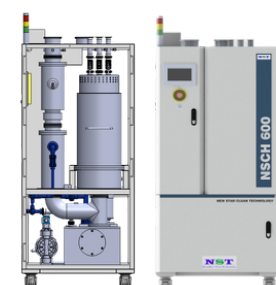
Plasma & Wet Type Facility



Application & Features:

- Designed for semiconductor facilities such as CVD, Diffusion, and Etch processes
- Available in Plasma and Wet type configurations
- Capacity options: 600 slm, 1000 slm, and 1500 slm
- Compact system size of 1100 × 950 × 1800 mm
- Average power consumption: 5 kW
- System weight: 550 kg
- Torch core temperature up to 3000°C
- Capable of handling NF₃, SF₆, CF₄, and other PFC gases
- Processing efficiency up to 99%
- Optional accessories include acid gas absorption tube and nitrogen oxide absorption cylinder

Heat & Wet Type Facility



Application & Features:

- Designed for semiconductor facilities such as CVD, Diffusion, and Etch processes
- Available in Heat and Wet type configurations
- Capacity options: 600 slm, 1000 slm, and 1500 slm
- Compact system size of 800 × 850 × 1700 mm
- System weight: 450 kg
- Heating temperature up to 750°C
- Mainly designed for flammable gas handling
- Features high removal efficiency
- Equipped with a special heater module
- Uses less coolant compared to other systems

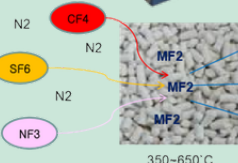
Dry Type Facility



Application & Features:

- Designed for semiconductor facilities such as Implant, Etch, and CVD processes
- Available in Dry Type configuration
- Capacity options: 80 L, 100 L, and 200 L
- Compact system size of 800 × 800 × 1800 mm
- System weight: 380 kg
- Equipped with auto bypass and mini-tank backup
- Features dry contactor interface

Heat & Catalyst (Dry) Type Facility

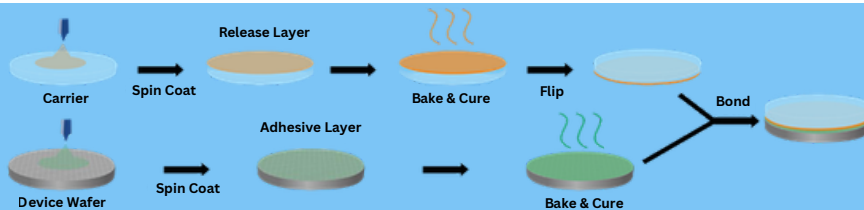


Application & Features:

- For CVD and Etch applications
- Suitable for small-flow, high-concentration gas treatment
- Capacity: <100 slm
- Size: 800 × 850 × 1800 mm
- Power: Avg. 3 kW
- Weight: 450 kg
- Heating temperature: 300°C–600°C
- Handles NF₃, SF₆, CF₄, and other PFC gases
- Integrated catalytic absorption purifier
- Processing efficiency up to 95%
- Features low energy consumption and stable operation



Temporary Bond



Design Features

- TTV $\leq 3.0\mu\text{m}$
- No bubble and damage
- Center align $\leq 100\mu\text{m}$
- Bonding Temp. $\leq 350^\circ\text{C}$

SBN-08, ABT-08, ABT-12, ABT-08

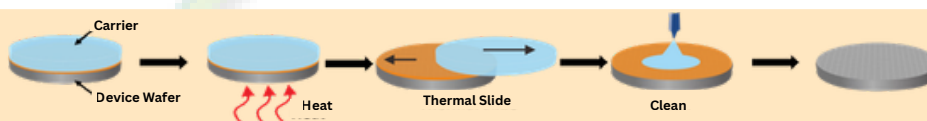
Temporary Wafer Bonder



Application & Features:

- Suitable for temporary wafer bonding of Si, GaN, SiC, GaAs, IGBT, Fan-Out, and TSV applications
- Supports wafer sizes from 2" to 12"
- Available in semi-automatic and fully automatic configurations
- Compatible with glue/wax temporary bonding processes
- Chamber configurations range from single chamber to multi-chamber
- Alignment options include mechanical alignment, pre-aligner, and mechanical clamp
- Delivers centering accuracy up to $\leq 50\mu\text{m}$
- Bonding force up to 60 kN
- Vacuum performance down to 7.6×10^{-2} mbar
- Bonding temperature up to 350°C

Thermal De-bond



Design Features

- Debonding Temp. $\leq 350^\circ\text{C}$
- No damage on Device site
- Carrier recycle
- High reliable SiCstage

Laser De-bond



Design Features

- Reliable Laser optical design, avoid heat effect
- Solid state laser UV ~ IR
- Top hat design, no damage on wafer device

SLC-12, ADC-08, ALC-12, ALP 12

Wafer De-Bonders



Application & Features:

- Suitable for wafer de-bonding of Fan-Out, TSV, Si, GaN, SiC, and IGBT applications
- Supports wafer sizes from 2" to 12"
- Available in semi-automatic and fully automatic configurations
- Offers both laser de-bonding and thermal de-bonding methods
- Chamber configurations range from single chamber to multi-chamber
- Alignment options include mechanical and optical alignment
- Clean module options include without cleaning, optional cleaning, and tape-off cleaning
- Compatible with frame or SiC carrier options depending on the model
- Equipped with digital force detection
- Vacuum performance up to ≤ 500 Torr / ≤ 700 Torr
- De-bonding temperature up to $\leq 350^\circ\text{C}$ for thermal process models



Purify Filter System (Polish & Saw Water Recycle)

Double Membrane Filter Press Facility



Application & Features:

- Sludge dewatering
- Wastewater treatment
- Industrial filtration processes
- High-efficiency solid-liquid separation
- First product developed by PASSAL
- Reliable and safe design
- Fully automatic operation
- Easy to operate and maintain
- Higher efficiency than competing products

Purifying Filter System Facility



Application & Features:

- Removes coarse particles and sharp objects before the UF stage
- Protects UF membranes from damage and clogging
- Reduces the purification load on UF membranes
- Extends the UF membrane replacement cycle
- Lowers overall purification and maintenance costs
- Widely used in semiconductor and high-tech industries

Slurry Washing System Facility



Application & Features:

- Fine chemicals, pharmaceuticals, pigments, and battery materials
- Graphene purification and heavy metal waste regeneration
- Waste silicon crystal and plastics processing
- Reliable and safe design
- Fully automatic operation
- Easy operation and maintenance
- High efficiency

AMG-5000



Application & Features:

- For thickness, flatness, surface shape, and warpage measurement
- Supports up to 12-inch patterned and non-patterned silicon wafers
- Nanometer-level optical inspection with high-precision morphology scanning
- Suitable for advanced IC process nodes (>3 nm) and HVM environments
- Helps improve wafer and chip production yield

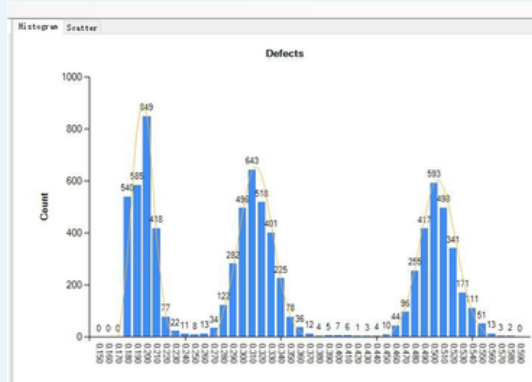
AP Series



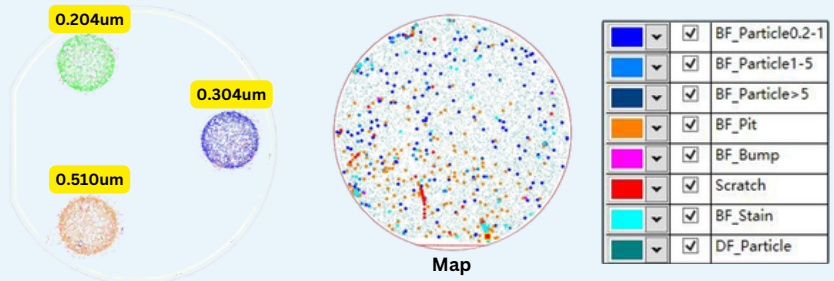
Application & Features:

- For non-patterned wafer defect detection in front-end processes
- High-precision inspection with accuracy from 60 nm to <20 nm
- Suitable for advanced IC fab environments
- AP7 launch expected in Q4 2025

Particle Counter



SiO on Si	Total Defect Count	Scratch	Pit	Bump	Particle	Particle (diameter bin.um)				Stain (Area>250um*2)
						0.08~0.2 (DF_Particle)	0.2~1	1~5	>5	
SiO	12116	39	928	4	11032	9064	1386	258	324	113



靖洋集團控股有限公司
 Genes Tech Group Holdings Co Ltd.

TEL Refurbish Machine

Used MARK 7/8 ACT/12
 Photolithography



Turnkey Service:

- Tool
- Refurbishment
- Modification
- Installation
- Warranty

Used VDF/VCF-615S
Alpha 8S/SE Alpha 303i
 Deposition & Difuffusion



Turnkey Service:

- Tool
- Refurbishment
- Modification
- Installation
- Warranty

Used Unity Series
Telius Series Certas/Vigus
 Dry Etching



Service:

- Installation



Used Tool Nikon Canon Stepper / CD SEM

Used Nikon Stepper
(G6/G7/i7/i8/i9/i10/i11/i12)



Photolithography

Used Nikon Stepper
(i4/i5/i5+)

Application & Features:

- For photolithography applications
- Turnkey solution including installation, overhaul, upgrade / modification, and service warranty

Hitachi (Used)
S8xxx /S9xxx



CD Measurement System

Application & Features:

- For CD measurement on opaque, semi-transparent, and transparent wafers
- Configurable wafer size depending on system specification
- Measurement range from 0.1 μm to 10 μm ; manual mode for patterns ≥ 50 nm
- High accuracy: $3\sigma \leq 0.005 \mu\text{m}$ (AFC off), $3\sigma \leq 0.01 \mu\text{m}$ (AFC on)
- SEM image magnification from 500 $\times$ to 150,000 $\times$



多海企業有限公司
KUNG HAI ENTERPRISE CORP.

Semiconductor Level : Non-Seal / Chemical Resistant / Non-Metallic Material Pump, ATEX Certificated (Europe)

Sealless Magnetic Drive Pump

Non-Metallic Material GFR-PP & CFR-ETFE



Application & Features:

- For chemical, semiconductor, electronics, and wastewater industries
- GFR-PP / CFR-ETFE for high corrosion resistance
- Sealless, leak-free design
- For corrosive, toxic, flammable, and explosive chemicals
- Easy maintenance with efficient cooling design
- CE / ISO / ATEX certified

Dry Run Protector

Prevent Pump Dry Running Current Type (A) & Power Type (Kw)



Application & Features:

- For pump safety and dry-run protection
- Available in Current (A) or Power (kW) type
- Automatically stops pump during overload or underload
- Prevents damage from dry running, low flow, or closed valve
- Compact design for easy installation
- Improves system stability and reduces downtime

Sealless Magnetic Drive Pump

Stainless Steel Material Standard for SUS316L



Series : PM and PS

Application & Features:

- For semiconductor, PCB, optoelectronic, electronic, hydrogen energy, and CCS industries
- SUS316L stainless steel for corrosion-resistant and high-purity applications
- Sealless, zero-leakage design for safe chemical handling
- Energy-saving, easy maintenance, and low operating cost
- Customizable design with CE / ISO / ATEX certification



Series : PM and PL

Application & Features:

- For semiconductor, chemical, PCB, optoelectronic, wastewater, hydrogen energy, and CCS applications
- Award-winning stainless steel magnetic drive pump series from Taiwan
- Sealless, zero-leakage design for hazardous liquid transfer
- Suitable for corrosive, toxic, flammable, and explosive liquids
- Customizable for different flow, pressure, and temperature conditions



cmit 政美應用

**Comprehensive Metrology & Inspection Solutions:
Advanced Packaging AOI 2D/3D**

Argus

Multilayer Intermediate Layer (RDL) Inspection System

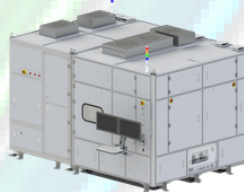


Application & Features

- High-precision multilayer RDL inspection
- Reduced imaging interference via optimized optics & algorithms
- 2 μm / 2 μm resolution with full-spectrum illumination
- Defect sensitivity down to 0.7 μm
- Supports 6", 8", 12" wafers and 310 $\times$ 310 mm panels
- Wafer thickness: 400–2500 μm ; die size up to 280 mm
- Optional: micro-bump 3D measurement, fluorescence detection, film thickness, differential control

Phantom

Large-size Panel Inspection + 3D Bump Measurement System

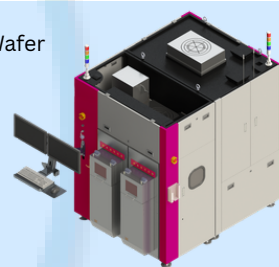


Application & Features

- Large-area panel inspection for advanced packaging
- Supports multilayer RDL processes (FOPLP, CoPoS, chiplet integration)
- Designed for large-scale manufacturing process control
- Supports panel sizes: 510 $\times$ 515 mm, 600 $\times$ 600 mm, 700 $\times$ 700 mm
- Panel thickness: 400–4000 μm ; warp tolerance < 10 mm
- All-light-source module for multilayer RDL
- Single scan with integrated multi-parameter detection (focus, magnification, illumination, sensitivity, engine)
- Optional: micro-bump 3D measurement, fluorescence detection

Buffalo

2D Inspection of Wafer Cutting



Application & Features

- Post-dicing wafer inspection
- High-speed, high-sensitivity detection of cracks, chipping, and particles
- Supports automated handling for 8" and 12" film frame carriers
- High-magnification defect detection and measurement
- Bright field, dark field, and multi-wavelength illumination
- Instant high-magnification color imaging
- Detects dicing defects: cracks, scratches, chipping, breakage



多米諾自動化科技股份有限公司
DOMINO Automation Technology Co., Ltd

CMP Process Tool

GP/GPR/GPAS Series

Patented Glass Polishing Machine

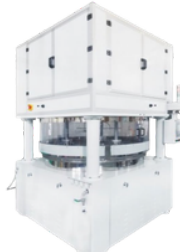
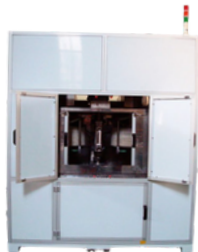


Application & Features

- TFT glass processing for sizes G3.5 to G8.5
- Polishing precision within 2 μm / 30 cm^2
- Material removal rate: 8–12 μm per 20 min cycle
- Integrated semi-automatic / fully automatic loading and unloading

Multi-axis Polishing Machine, Edge Polishing Machine, Wafer Grinding Machine

FPD Processing Equipment



Application & Features

- Precision machining solutions for the flat panel display (FPD) industry
- In-house R&D and manufacturing
- Equipment portfolio includes:
- Wafer grinding machines
- Multi-axis grinding and polishing machines
- Vacuum laminating machines
- OGS prism polishing machines

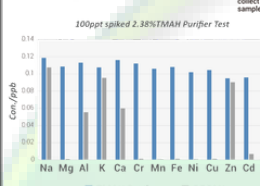
Litho + Purifier

Purifier Product Scope



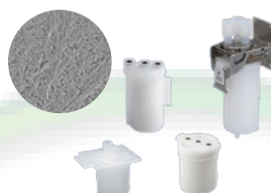
- Nylonpolar™ Purifier (NPL)
- lonGard™ SL Purifier (MGS)
- PlusGard™ Chelate Purifier (PGC)
- Chemdeion™ Purifier (CHP)
- lonGard™ Aqua Purifier (MGA)
- lonGard™ DL Purifier (MGD)

Metal Purifier for TMAH Developer Solution

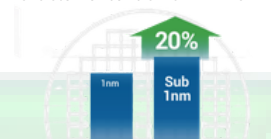


New Advanced PE sub 1nm Litho Filter

New Sub 1nm PE

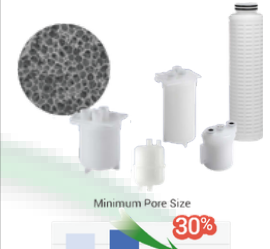


Particle Retention on 2nm GNP



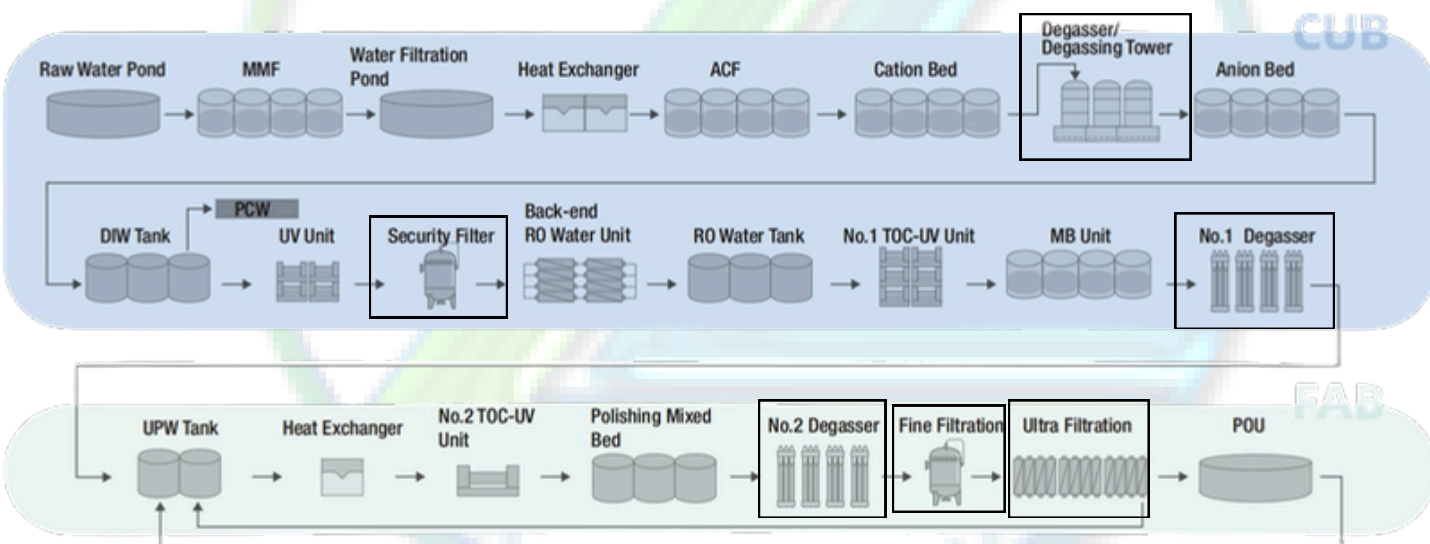
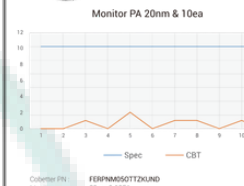
Photoami™ PI sub 1nm Litho Filter

Sub 1nm PI Photoami



Photogile™ FER POU Filter for NTD

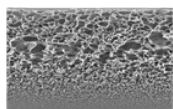
2nm PTFE Photogile FER



Wet + CMP

Filtration Solutions for Wet Etch & Clean

- Novacon™ sub 1nm HAPES
- Highly Asymmetric PES membrane
 - High flow rates



- Chemrapid™ 2nm PTFE:
- Modified PTFE Membrane
 - Excellent chemical compatibility
 - Very low metal extractables



All Fluoropolymer Filter Housing Fluorolink™

CMP Slurry Filtration Solution



Keevalid™ & Keevalid™ II
Rolled or Melt-blown Depth PP Medium for CMP
30nm - 150µm

Pleavalid™
Pleated PP Medium Filter for CMP
50nm - 40µm

Nylonvalid™
Nylon Membrane Filter for CMP
50nm - 0.45µm

Plusvalid™
PES Membrane Filter for CMP
50nm - 0.45µm

Dualvalid™
Patented Construction Filter for CMP
50nm - 5.0µm



FROM EQUIPMENT TO SMART MANUFACTURING

AI DRIVES SEMICONDUCTOR EXCELLENCE

1

FOR EQUIPMENT MANUFACTURERS
Smarter Equipment



Equipment



AI SCADA
Built for Semiconductor



AI Equipment

Turn Machines into Intelligent Assets



AI Capabilities

Just Talk, It's Done.

- No Code. No Drag & Drop. No Configuration. No UI Design.
- Tell AI what you need.
- Instantly Generate Beautiful HMI & SCADA Project.
- Free Your Engineers. Focus on Innovation, Not Engineering.
- Show me the equipment OEE, alarm trend and chamber temperature on one screen.

Use Cases



Value-added for OEMs



Differentiated Equipment



Smart After-sales Service

2

FOR END USERS
Smarter Manufacturing



AI Equipment



Prodia
Industrial AI Agent



AI Smart Manufacturing

From Data to Decisions. From Decisions to Better Results.



Prodia

Why is the yield dropping on Line 3 today?

Prodia Recommendation:

- Chamber pressure fluctuation detected. Likely impact on film uniformity.
- Clean the throttle valve and run recipe optimization.
- Predicted yield improvement: 1.8%

Use Cases



Improve Yield & Productivity



Enhance Quality & Traceability



Lower Cost & Boost Efficiency

KEY BENEFITS



Higher Efficiency
5-15% OEE Improvement



Less Downtime
30-50% Less Equipment Failure



Better Quality
1-3% Yield Improvement



Smarter Decisions
AI-driven Continuous Optimization

NEXT-GEN INDUSTRIAL AI SOLUTIONS



ZILIAN
子聯有限公司

SINGAPORE

•新加坡

MALAYSIA

•馬來西亞

TAIWAN

•台灣

Zi Lian Smart Cabinet

Intelligent Cabinet System

Secure. Traceable. Efficient.



Intelligent Stocker Cabinet for Autonomous Storage

Smart Storage Control System

Secure, traceable and intelligent storage for spare parts, tools and consumables

Smarter Storage. Better Control. Higher Productivity.
Designed for next-generation semiconductor operations.

Application

- Spare parts management
- Tool and consumable control
- Controlled withdrawal process.
- Maintenance support

Features



Smart Item Control

Manage critical items with better visibility, status tracking and usage control.



Wrong-Part Prevention

Help prevent incorrect withdrawal and reduce the risk of using unsuitable parts.



Traceability Record

Maintain digital records of access, withdrawal, return and usage history.



PM Due Tracking

Keep maintenance-related items under control with due date monitoring.



Secure Access Control

Allow only authorized users to access specific items aban on user level.

Applicable for varies wafer shippers:

FOUP/FOSB(12")/Coin Stack/HWS/POD(8")/Reel/Jedec Tray

Features:

- AGV performs inbound and outbound tasks between CPU, Stoker E-rack, and shipping dock according Information Control System.
- Bar Code/RFID material-account comparison to accurately grasp the capacity utilization rate



Wafer Carrier Packing & Unpacking System

- RFID/Info Pad removes/Attach functions to save the cost
- Module Parameter setting: Sealing time, temperature, vacuum extracting time ... etc., in the APK system.
- N2 Purge to ensure product quality in the APK system.
- Waste Bags and Desiccant Recycling in the UPK system.

Container (Hi-Box) Packing & Unpacking System

- RFID identification to detect product inbound or outbound
- Container PP bundling strap automatic strapping & Removing
- Container Load cell weighting before outbound

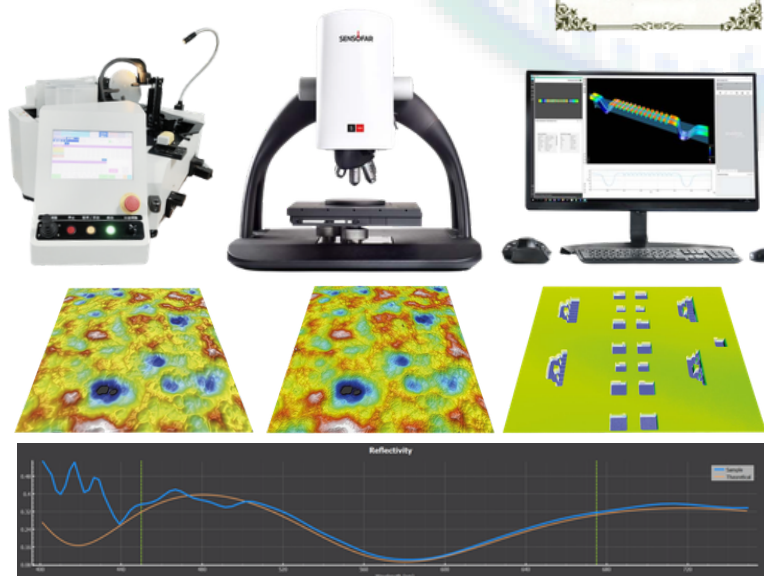
- Smart warehouse with intelligent E-Rack and Trackless automatic transport AGV to combine with Information Control System, seamlessly integrate into the intelligent factory.

AGV/AMR & Stacker

SENSOFAR

Sensofar Metrology

S neox 3D Optical Profiler



Application

- Areal 3D surface metrology for:
- Quality Control (QC): automated procedures, 24/7 operation, pass/fail reporting
- Research & Development (R&D): flexible lab measurements with minimal compromise across surface types

Features

High speed:

- 180 fps data acquisition; standard measurements ~5× faster than previous generation; "fastest areal measurement system"

Easy to use:

- one-click operation; intuitive UI; configurable software modules

QC automation:

- user access rights, recipes, barcode/QR compatibility, customized plugins, automatic pass/fail reports (SensoPRO)

3-in-1 measurement (single sensor head):

- Confocal
- Interferometry
- AI Focus Variation

Thin film thickness:

- transparent layers 50 nm to 1.5 μm measured in < 1 s; spot diameter depends on objective (~0.5–40 μm)

LED illumination:

- fewer laser artifacts (interference/scatter), faster area illumination, ~50,000 h lifetime, multiple wavelengths

Validation & traceability:

- calibrated with traceable standards per ISO 25178 (parts 600 & 700) for Z factor, XY scale, flatness, noise, parcentricity/parfocality; includes accuracy & repeatability verification

High resolution / low noise:

- nanometer-level system noise; example cited 0.3 nm topography capability

DIC observation:

- differential interference contrast (Nomarski prism) to enhance very small height features (sub-nanometer scale visibility)



Spin Rinse Dryer SV SH SRD

Spin Rinse Dryer

Vertical cyclone dryer SV Model



Application & Features:

- For drying wafers, substrates, and glass after cleaning
- Vertical and horizontal models for different wafer sizes and batch capacities
- High-speed spin with N₂ blow for fast, stable drying
- Long-life motor with low-vibration rotor design
- Includes purification, speed, temperature, and static control
- Touchscreen interface with GEM / SECS-II support

Spin Rinse Dryer

Horizontal cyclone dryer SH Model



Application & Features:

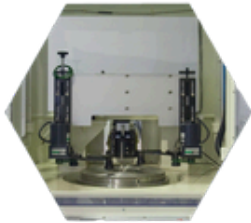
- For drying wafers, substrates, and glass after cleaning
- Horizontal and vertical models for different wafer sizes and batch capacities
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- Includes purification, speed, temperature, and static control
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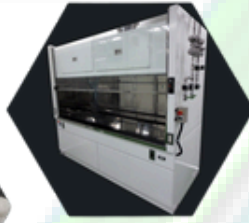
CWE

Reclaim Compound Semi-con Wafer - SiC GaN InP

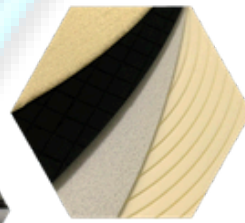
Polishing Machine



Draft Chamber



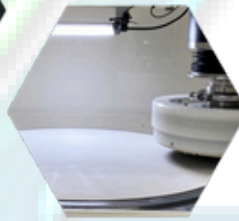
Polishing Consumables



Washing Machine



Processing Service



Various Substrate Sales



復華機械股份有限公司 FU-HWA MACHINE CO., LTD

Metal Carrier + Jig

Metal Cassette
Facility



High Temperature Wafer Cassette
Oven & Curing



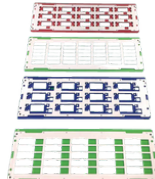
Frame Wafer Cassette (Saw & Grinding)
Oven & Curing



Metal Cassette
Oven & Curing



Carrier Boat/Cover
Oven & Curing



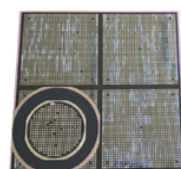
Wafer Frame/Ring (Saw & Dicing)
Oven & Curing



LED Wafer Carrier/Cassette
Oven & Curing



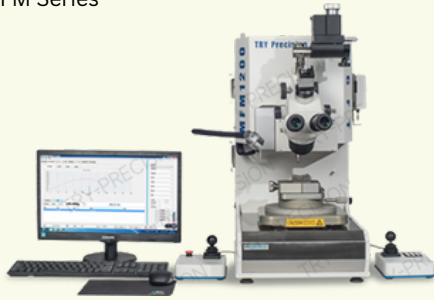
Panel Fan Out
Oven & Curing



Wafer Fan Out
Oven & Curing



MFM1200L
MFM Series



Application

- Manual tester for tensile and shear testing
- For semiconductor, LED, and high-reliability applications
- Supports destructive and non-destructive testing
- Optional modules: cold/hot bump pull, forceps tension, passivation shear
- User-friendly software with SPC system compatibility
- Standard 100 × 100 mm XY stage
- Auto-Range (no manual sensor setup required)
- Max shear force up to 200 kg

MFM1500HF Heavy Shear Force Tester
MFM Series



Application

- Manual tester for tensile and shear testing
- High-force testing up to 1000 kg shear force
- Customizable configurations for specific requirements
- Supports multiple test modules
- Precision XYZ motion (X: 150 mm / Y: 150 mm / Z: 75 mm)
- Designed for large and high-strength samples

ABT2000C Bond Tester
ABT Series



Application

- Fully automatic bond testing for semiconductor, advanced packaging, automotive electronics, SMT, and power devices
- Magazine-to-magazine batch testing with automated loading/unloading
- Integrated process: PR alignment, dynamic force measurement, data analysis, and upload
- Unmanned operation with minimal manual intervention
- I-SEE intelligent image recognition (3-level) for precise positioning and repeatability
- Advanced dynamic force measurement and high-accuracy positioning control
- Trinocular microscope with HD camera for monitoring and recording
- Alarm system for missing/full magazines
- Adjustable magazine handling system (clammer, rails, carriers)



Replacement Machine: TD-011F for SMC INR-498-011C

TD-011F (Heat Exchanger / Temperature Control Unit)
Replacement for SMC INR-498-011C



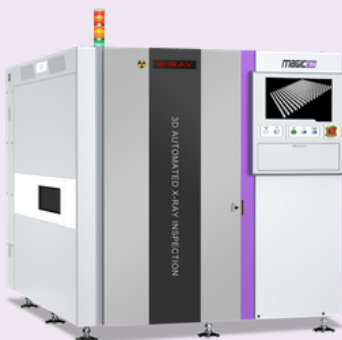
Application & Features:

- Temperature control and heat exchange for semiconductor processes
- Replacement for SMC INR-498-011C; customizable for industrial equipment
- Temperature range: 20–80°C; stability $\pm 0.2^\circ\text{C}$
- Cooling capacity: 40 kW; heating: 20 kW
- Pump: up to 80 m head / 120 L/min flow
- Tank capacity: 60 L
- Fast-response IN/OUT (4 sets); remote communication compatible with SMC specs
- 4.3" HMI with monitoring (temperature, level, pressure)
- Comprehensive protection: overheat, low/high level, sensor fault, overcurrent, low pressure
- Power: 3 ϕ 220V, 50/60Hz; compact design
- Customizable: power, flow/pressure, temperature range, control accuracy, I/O, remote control, SPC monitoring



High-Power 30 X-ray Inspection Machine

High-Power 3D AXI
High-Power 30 X-ray Inspection Machine



Core Technology and Advantages:

- Automatic 3D Inspection Algorithms
- MagicAI Multi-Type Defect Training Platform
- 3D Image Analysis Function
- HiP Combination Algorithms
- PCB Back Drilling Inspection
- AI Noise Denoising Technology

Application & Features:

- For PCB back drilling, PCBA, and semiconductor IGBT inspection
- Supports BGA/LGA/CSP, QFN/QFP/SOP, DIP, PoP, connectors, power modules, and more
- Up to 1.4 s/FOV inspection speed
- 3 μm resolution for small BGA inspection
- Flexible settings for different applications
- Three-view imaging (XY / YZ / XZ) for easy defect analysis
- MagicAI platform for automatic multi-defect detection

HPDB100

2-in-1 Flip Chip & Die Attach Machine



Wafer Size

- Up to 8" (200 mm) wafer
- Also supports Waffle Pack / Gel-Pack

Application

- Flip chip die attach
- Standard die bonding (die attach)

Features

- One machine supports both flip chip and die attach; easy and fast process changeover
- Standalone epoxy and bond stage
- Up-look & down-look optics table for precision alignment
- Supports various epoxy stamping processes
- Supports normal die bonding process
- Optional: flux dipping & flip chip die attach
- Optional: DAF process
- Optional: UV curing
- Auto wafer expand
- Auto substrate loader & unloader
- Supports SMEMA connection
- Bond arm: programmable bond force (VCM), 20–500 g



Photomask for Semiconductors

Newway Semiconductor Photomask

(process capability: 40 nm, roadmap to 28 nm)



Application

Integrated Circuits (IC):

- MCU, CIS, DDIC, PMIC, etc.

Advanced Packaging:

- TSV, TGV, CPO, FOPLP, COF, FC, BGA, etc.

Semiconductor Devices:

- Discrete Devices, MEMS, Compound Semiconductors, Power Semiconductors, etc.

Pan-Semiconductor Display:

- Micro-LED, Micro-OLED, LCOS, etc.

Features

- Widely used for IC, semiconductor devices, advanced packaging, and related fields
- Achieved 40 nm node via investment in Luxin Semiconductor; planned expansion to 28 nm
- Multiple mask sizes available with Soda / Quartz / Quartz & Soda materials
- Minimum L/S down to 0.5 μm (6025, Quartz)



Professional Solder Materials: Under fill, Flux, Solder Paste, Solder Bar, Solder Ball ..

Advanced Materials Development Center

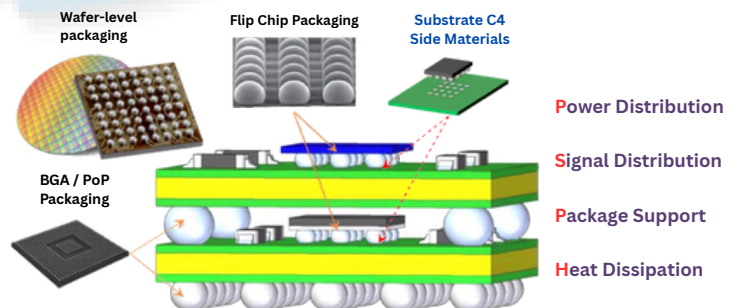
SMT Process System



Wafer Bumping System



Application & Feature:





ZILIAN
子聯有限公司

SINGAPORE

•新加坡

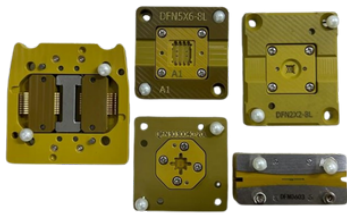
MALAYSIA

•馬來西亞

TAIWAN

•台灣

Conversation Set



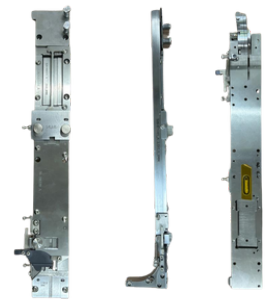
Socket



Test film/
Golden finger



Socket for turret sorting
machines



Tungsten steel test pieces,
standard test pieces, irregularly
shaped test pieces



ZILIAN
子聯有限公司

SINGAPORE

•新加坡

MALAYSIA

•馬來西亞

TAIWAN

•台灣

Oven Monitor System

Chamber Monitoring

Monitoring of all chambers temperature and humidity performance



Chamber Monitoring

Monitor all chambers with running status and alarm summary



Traceability Record

Record door access, temperature and humidity history



Door Open Tracking

Track door open/close events and unauthorized access



Secure Access

Ensure only authorized users can open specific chambers



Warning & Alarm

Get warnings and alarms for over limit events



Performance Analysis

Analyze temperature and humidity trends of each chamber



ZILIAN
子聯有限公司

SINGAPORE

•新加坡

MALAYSIA

•馬來西亞

TAIWAN

•台灣

Ultratech Stepper Solutions

AP200/300

Lithography System

Repair, Refurbish, 4-Re



Global Top 1 Team

Turn Key:

- 2nd tool, Repair, Refurbish, Process

Tool, Device & Software Upgrade

- All model: 1000 ~ 1900,
- **Titan, Saturn, Spectrum**
- **AP200, AP300 Series**

Application & Features

- For advanced packaging, LED, MEMS, and power devices
- Suitable for copper pillar, fan-out, TSV, silicon interposer, RDL, and micro-pillar applications
- Built on Veeco's Unity Platform™ for high automation and cost-effective manufacturing
- Delivers 2 μ m resolution, high throughput, and large depth of focus
- Supports dual-side, IR, and machine vision alignment
- Features warped wafer handling, field stitching, and SECS/GEM automation

Cleanroom Supplies, ESD Protection & Equipment



Cleanroom Wipes



Cleanroom Wipes



Dust Removal Sticky Stick



Ionizing Fan


 COB Adhesive for Chip Cleaning,
Bubble Gum


Antistatic wrist straps


 Cleaning Dust-free Wiping
Cloth


Antistatic Gloves

DAINICHI Foup Carrier Cassette

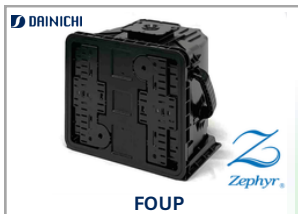
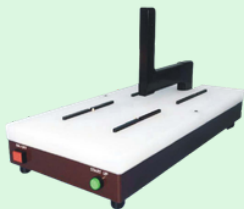
 FOUP	 SMIF Pod	 RSP	 Mask Case	 Wafer Carrier/Handle
 Box	 Chip Tray	 Chip Trays and Accessories	 Tuck Carrier	 Metal Cassette

Table Auto Wafer Transfer Tool

Auto Wafer Transfer



Wafer Size

- 4 inch-8 inch

Application

- Semiconductor and optoelectronics production lines
- Wafer transfer between wafer cassettes

Features

- Material: PP / ESD
- Customized specification
- Fool-proof positioning: cassette cannot operate unless correctly placed
- Automated transfer reduces wafer breakage and labor loss
- EMS emergency stop: stops immediately if POD leaves position or in emergency

Wafer Aligner



Wafer Size

- 2 inch-12 inch

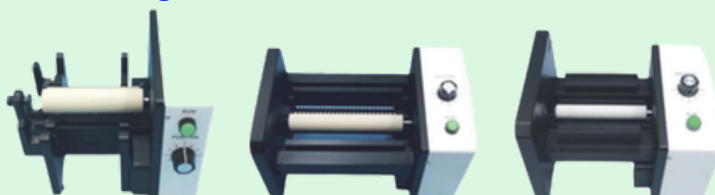
Application

- Wafer batch alignment assistance (flat/notch alignment)

Features

- Material: PP / POM / ESD
- Customized specification
- Fast, accurate wafer alignment at any angle

Auto Wafer Aligner



Wafer Size

- 4 inch-8 inch

Application

- Automatic wafer batch alignment (flat/notch)

Features

- Material: POM / ESD
- Customized specification
- Fast, accurate alignment at any angle
- Multi-section fixed angles adjustable per requirement



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High-End Quartz Material Solution: Semiconductor Level Quartz

Semiconductor Grade Quartz Plate



Application & Features

- Semiconductor manufacturing with ultra-high purity and strong chemical resistance
- Optical components with high transmission and clarity
- High-temperature processing with excellent thermal stability (up to 1500°C) and low thermal expansion
- Chemical and laboratory environments with superior corrosion resistance
- Electrical insulation parts with high resistivity and low dielectric loss

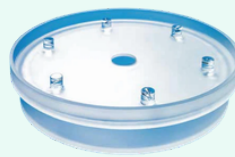
Quartz Heat-Treated Tube



Application & Features

- Silicon deposition and diffusion processes with high purity and precise dimensions
- Chemical reaction vessels with excellent corrosion resistance and sealing performance
- High-temperature environments with strong thermal resistance and long service life

Quartz Furnace Door



Application

- Silicon wafer diffusion equipment
- Other heat treatment furnaces/equipment

Features

- Maintains uniform and stable furnace thermal field
- Helps ensure consistent wafer processing quality

Quartz Feeder Tube



Application

- Feeder tube for monocrystalline silicon growth process

Features

- Made from solar-grade quartz tube
- Flame-fused ingot, high purity
- High strength
- Long service life



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Fluororesin Tube & Weld Fitting

Fluoropolymer Tube Fitting F80 Series

Flowell



Application & Features:

- For CD measurement on opaque, semi-transparent, and transparent wafers
- Configurable wafer size depending on system specification
- Measurement range from 0.1 μm to 10 μm ; manual mode for patterns ≥ 50 nm
- High accuracy: $3\sigma \leq 0.005 \mu\text{m}$ (AFC off), $3\sigma \leq 0.01 \mu\text{m}$ (AFC on)
- SEM image magnification from 500 $\times$ to 150,000 $\times$

Fluoropolymer Tube Fitting F80 Series

Flowell



Application & Features:

- For high-purity chemical and fluid piping systems
- Smooth inner surface for better flow and less fluid residue
- Bead-free welding design helps reduce leakage risk
- Maintenance-free, compact, and lightweight
- Automatic welding for consistent quality and safer operation
- Suitable for in-device welding with handheld operation



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Semiconductor Used Robot Refurbishment



BROOKS ATR7/AQR7 Robot Controller



BROOKS/PRI Pre Aligner



KAWASAKI Robot



AMAT VHP Robot



AMAT HP Motor



GENMARK Robot



GENMARK Robot



GENMARK Wafer Pre-Aligner



LAM/NVLS Vortex Robot ATM



Milara_Isel Serials Overhaul Repair



ISEL Robot



SANKYO SC3150 Robot Controller



RORZE RR304 Robot



YASKAWA Serials Overhaul Repair



YASKAWA Serials Overhaul Repair



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Authorized and Specialized in

Wet Etching Oxidation	Wet Stripper Scrubber	Chemical Etchant/ Stripper	Oven Furnace	Dry Etching Descum	Laser Explosion Stepper	Bonding Debonding	Refurbish Tool TEL/ Ultratech
Hitachi CD SEM	Metrology Particle Counter	Wafer Probe X-Ray	Track In-line Macro	Perfractional Filter UPW System, Chemical Delivery System, Gas System	Filter Press Local Scrubber	Smart Cabinet Smart Zi Lian	Ultratech Veeco Stepper Refurbish
CMP 4-Re Solution	Direct Lithography for Advanced Packaging	Semi S2/S8 Certificate FTIR On Site Gas Analysis	High Vacuum Plasma & Wafer Thinning Solution	Optical Inspection Tool	Non-Seal/ Chemical Resistant/Non- Metallic Material Pump	Used Tool Nikon Canon Stepper/CD SEM	Smart Microscope Macro & Micro
2D/3D AOI	Spin Rinse Dryer SV SH SRD	Sensofar Metrology	Wafer Carrier Warehouse Automation System	Filter Press Local Scrubber	Metal Carrier + Jig	Photomask	Professional Solder Materials
High-End Quartz Material Solution	Tube & Weld Fitting	Conversion Kit	High Precision Die Attach Equipment	Advanced Automatic Wafer Testing Technology	Table Auto Wafer Transfer Tool	Foup Carrier Cassette	Refurbish Machine

- Kaizen
- Upgrade
- Cost Saving



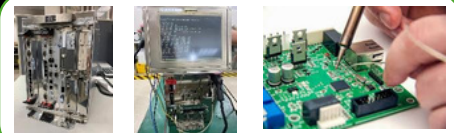
Refurbish

- Machine Refurbish and back to basic condition
- GenMark Robot
- Haskel Pump
- AIO Coater / Developer machine
- Process kit Machine
- Power Supply



Repair

- Machine Service / Troubleshoot
- Power Supply
- PCB Board
- Motor
- Controller



Replacement

- Obsolete consumers parts
- Consumer parts
- Optical Lens
- Ball mount machine wipe cloth
- Photoresist Pump



Replicate

- Reverse Engineering PCB
- Mechanical Fabrication
- Custom-made machine
- Drive train
- Diamond Disk

